

Digital System Integration in the Context of Industry 4.0

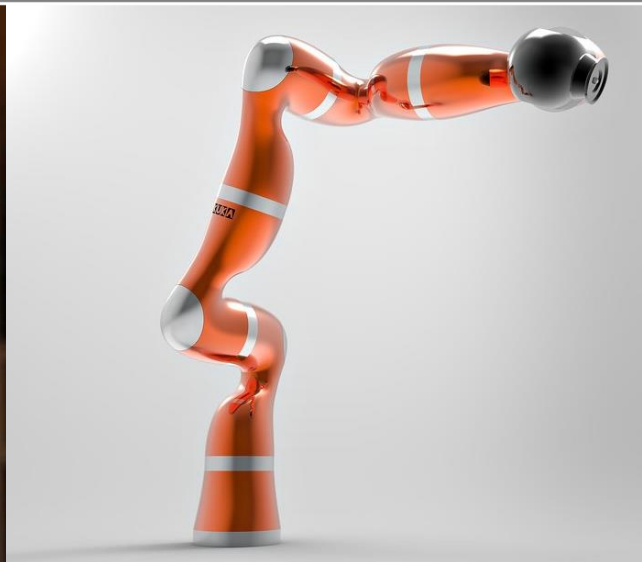
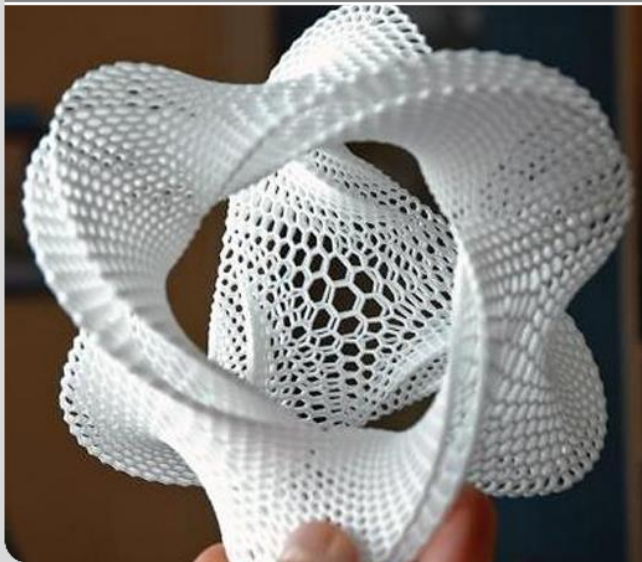
Digital Manufacturing

Keynote ACHI 2017

Dr. Steffen G. Scholz

22.03.2017

INSTITUTE FOR APPLIED COMPUTER SCIENCE

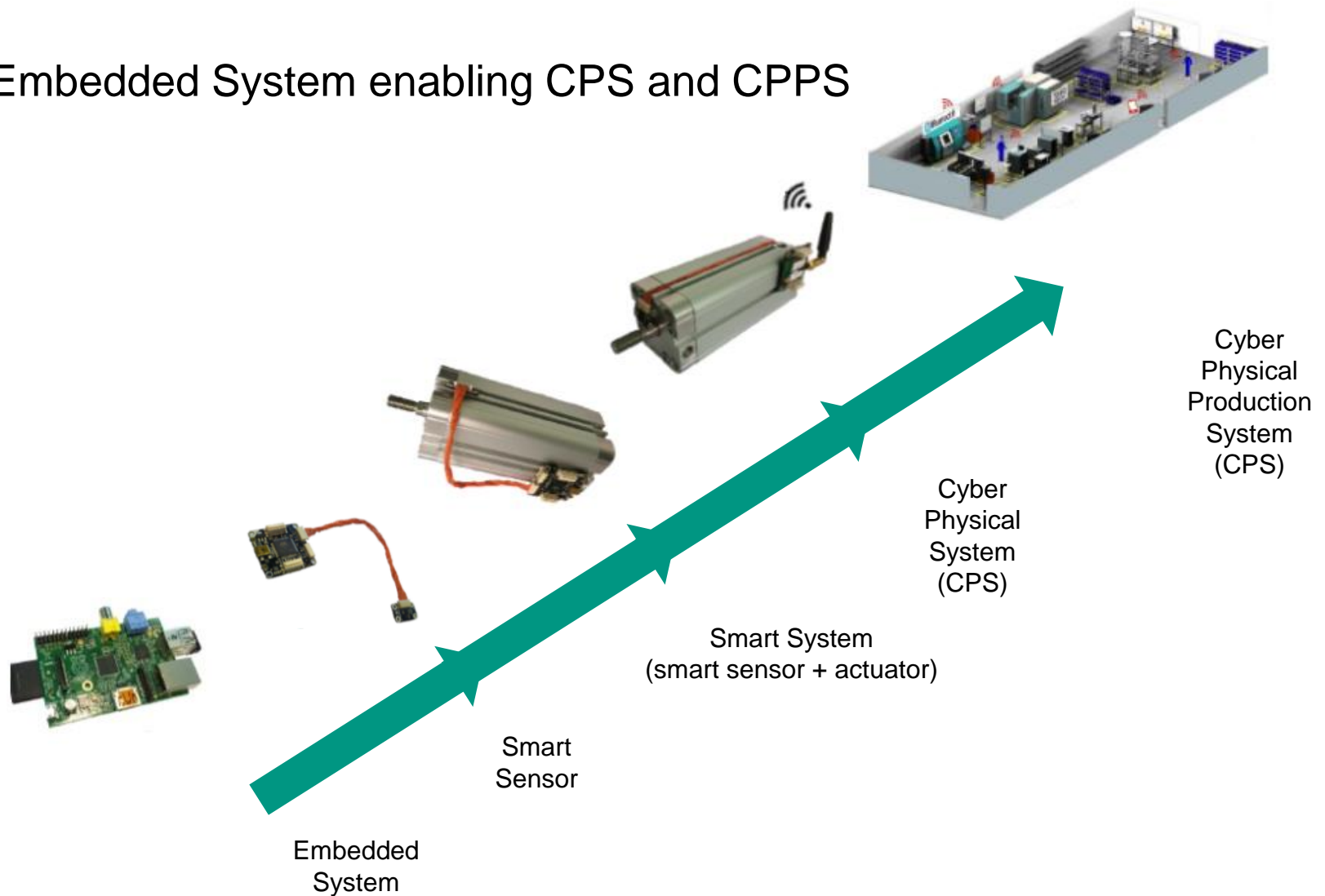


Overview

- Introduction
- Industry 4.0
- Flexible manufacturing
- Digital printing materials
- Tailored applications
- Conclusion

Introduction

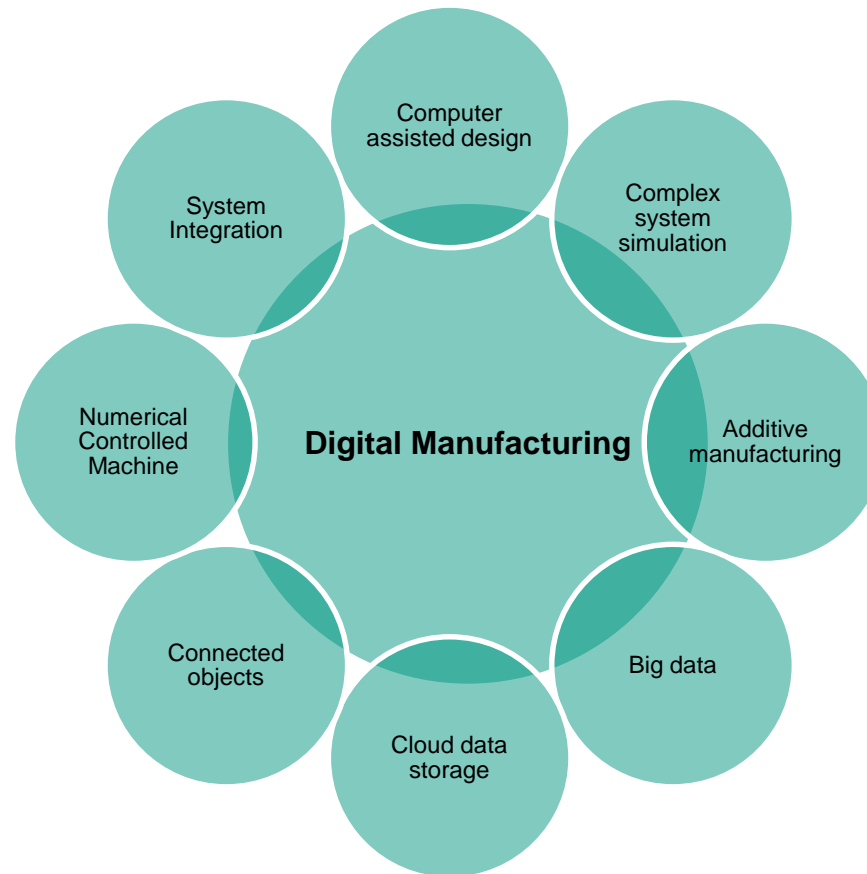
■ Embedded System enabling CPS and CPPS



Source: University Darmstadt

Introduction

- Convergence of information and operational technologies



INDUSTRY 4.0

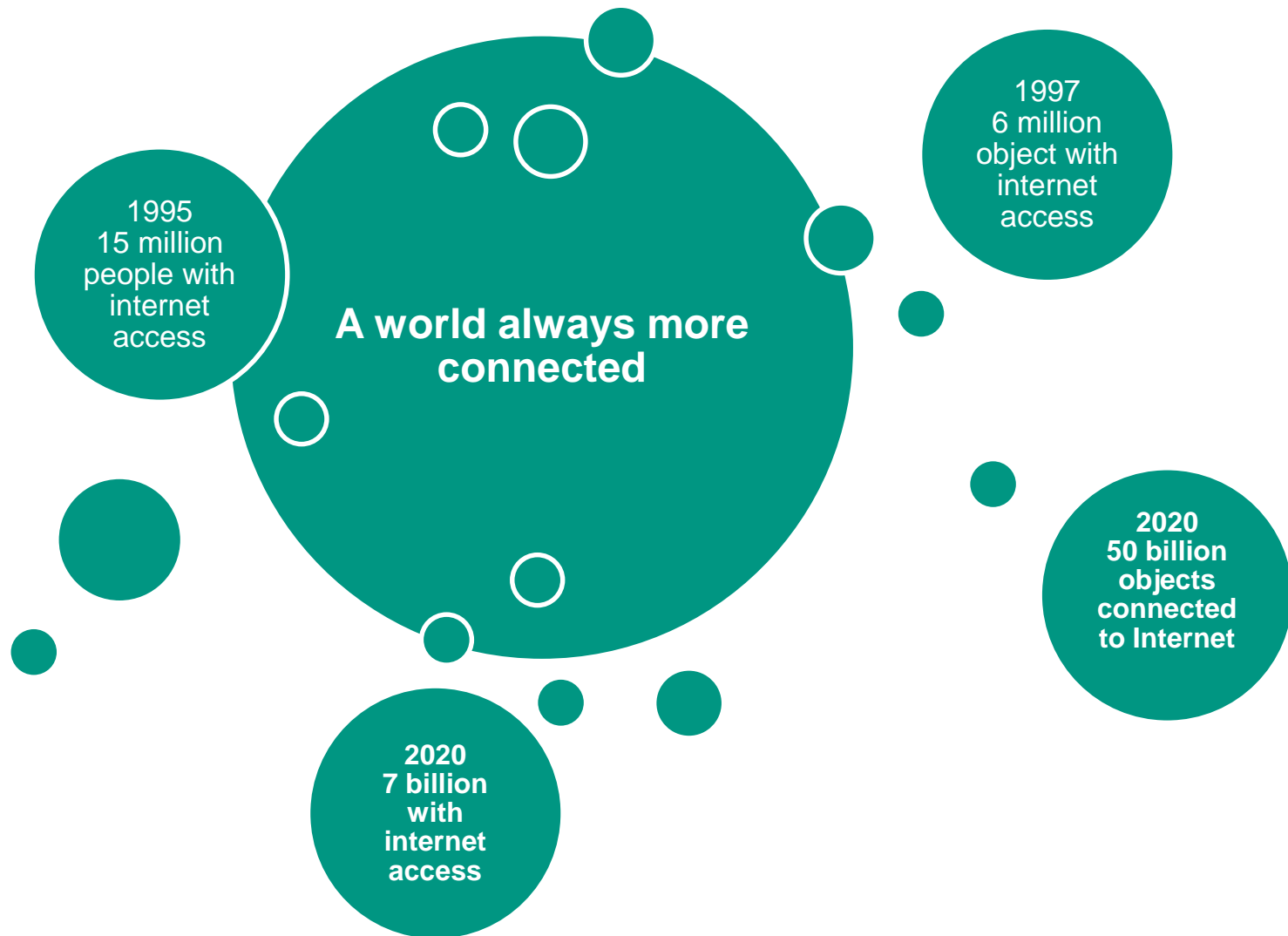
as part of the Internet of thing

The Internet of Thing

” We define the internet of things as sensors and actuators connected by networks to computing systems. These systems can monitor or manage the health and actions of connected objects and machines. Connected sensors can also monitor the natural worlds, people and animals. ”

McKinsey Global Institut

The Mission



Source: Bosch

Self organised and distributed artificial intelligence

Fast and automatic network integration , highly flexible

Open standards

Virtual real-time image

Digital integrated life-cycle-management

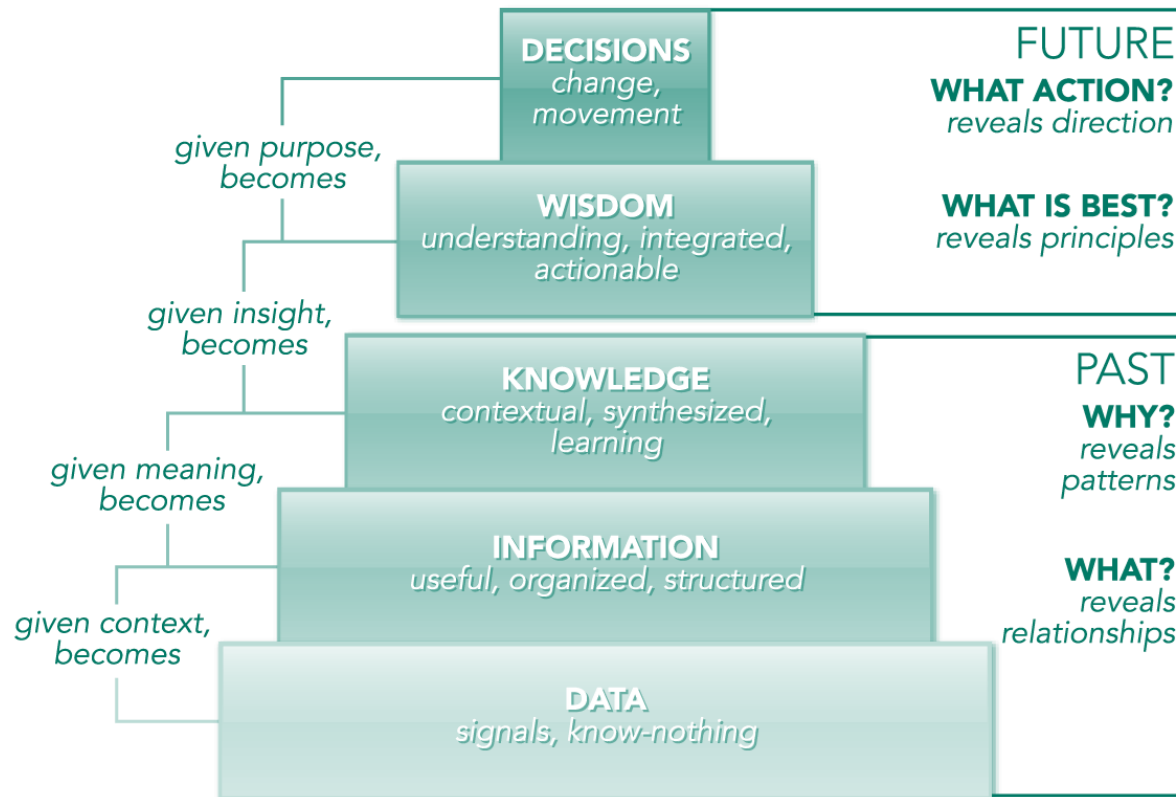
Safe and secure added-value networks

Humans as actors and in the centre



New paradigm

- How to compute the enormous quantity of data coming from sensors and convert it in value creation?



Source: AGT

Flexible Manufacturing Example: Project SMARTLAM



The consortium



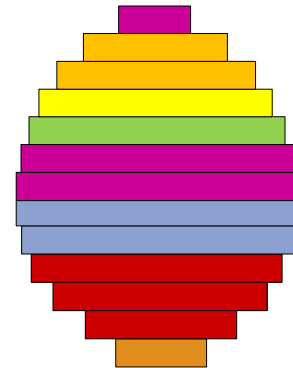
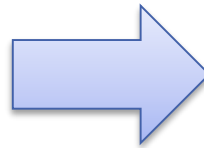
Project Duration: 2012/10-2016/01
Project Number: 314580
Project Volume: 4.1 mio Euro
Req. EC contribution: ca. 3 mio Euro

4 R&D partners
2 Technology partners
2 Reference customers

The ambitious vision



Design for traditional fabrication processes



Design for SmartLAM fabrication processes



Stacking of thin polymer films, each with specific properties utilizing advanced film material and surface properties for batteries, wiring, sensors and fluidics (structures and printed components)

Targets & topics

Project targets

- Capability to rapidly produce 3D mechatronic micro systems
- Increased flexibility and scalability of processes
- Reduced energy consumption
- Reduction of development and sale up time
- Product quality improvement
- Waste reduction and reduced impact on the environment



3D-I Modelling
& design approach



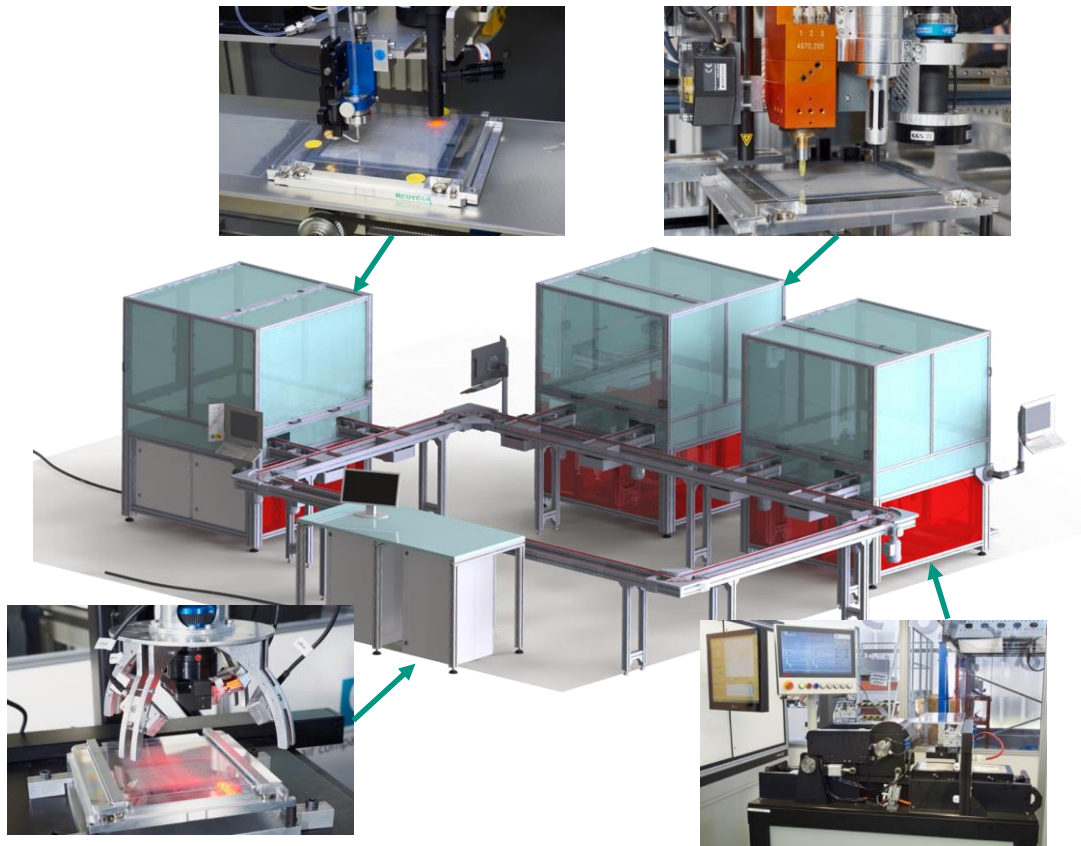
3D-I compatible
production platform



SMARTLAM
adaptive control and
vision inspection

R&D Topics

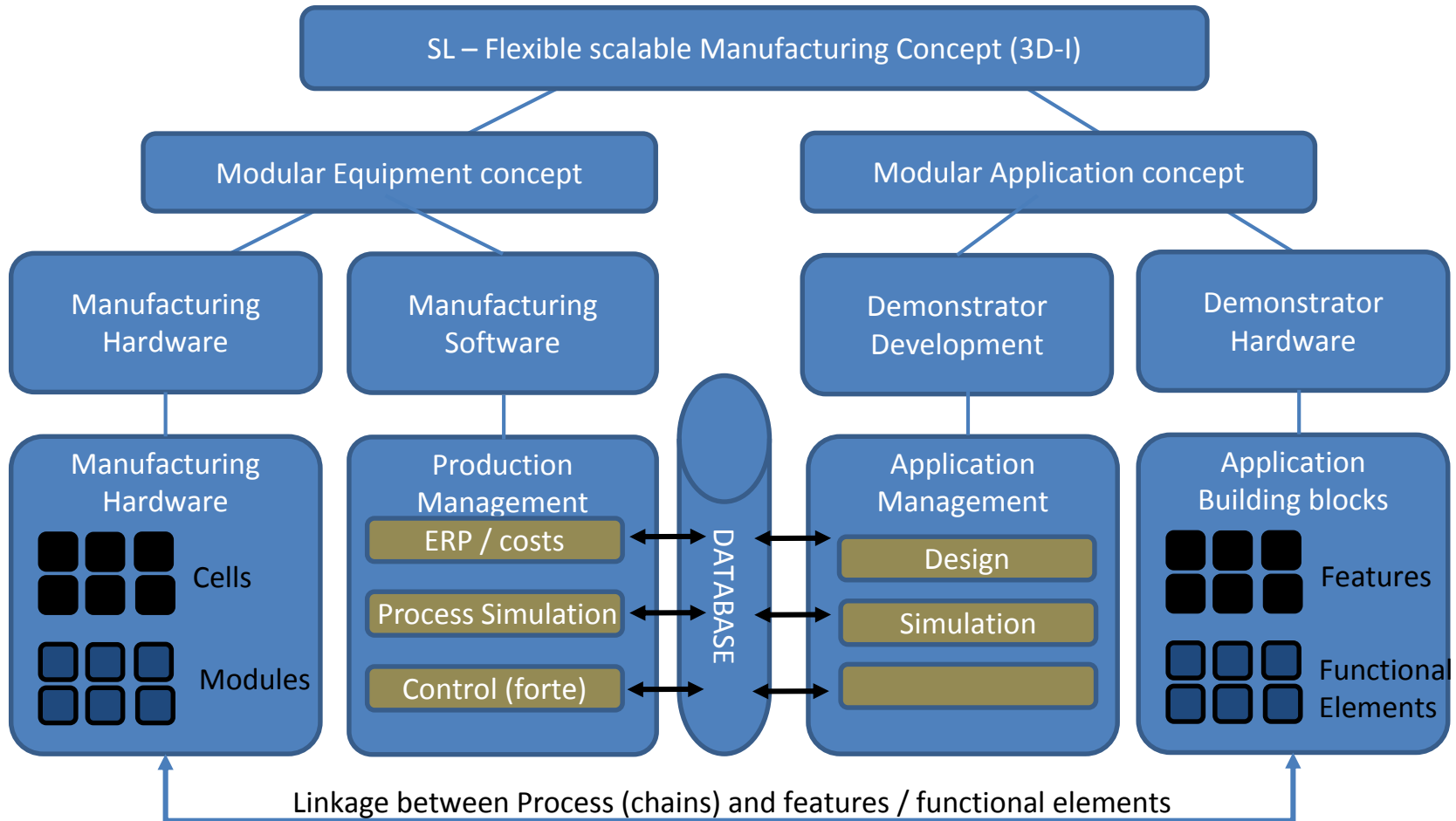
Modularity concept



- SMARTLAM 6 modules
 - Lamination
 - Laser welding
 - Laser structuring
 - Printing module (aerosoljet printing)
 - Assembly
 - Inspection

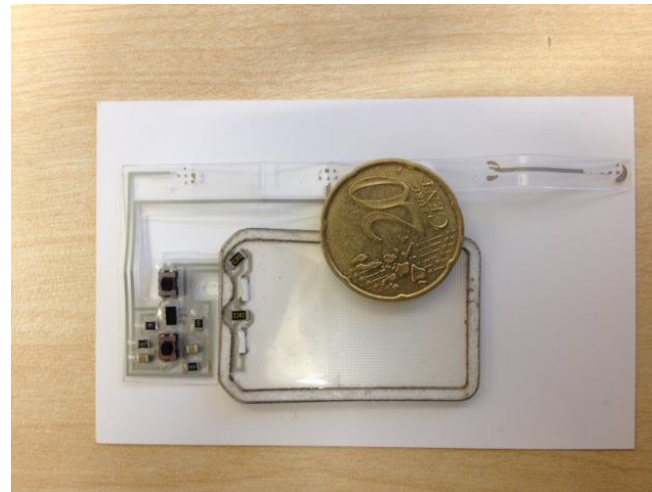
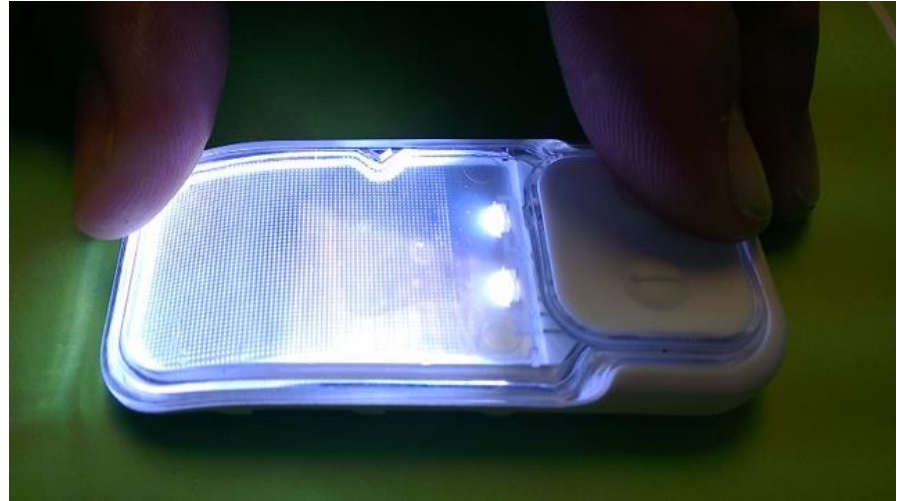


Project overview



Application 1 – LED lighting

- Light source embedded into surgical instrument
- Product includes 1. planar light-guide LED chip source, electronic control, switch and power source
- Sealed and to have high hermiticity for medical accreditation.
- Custom size and light specifications for different surgical procedures
- Specification will evolve over time
- Disposable
- Cost/volume critical – e.g. Veterinary market



Source: DLED

Additive Manufacturing in the context of Industry 4.0



Additive Manufacturing

Definition & Timeline

- Definition of AM:
 - „The process of joining materials to make objects from 3D model data, usually layer upon layer, as opposed to subtractive manufacturing methodologies, such as traditional machining“¹

- Typical technologies:
 - Laser/Light Polymerization (e.g. stereolithography)
 - Laser Melting (e.g. selective laser sintering, selective laser melting)
 - Extrusion processes
(e.g. fused filament fabrication, fused deposition modeling)
 - Material jetting (e.g. inkjet printing or multijet modelling)
 - Adhesive based processes (e.g. laminated object manufacturing)
 - Electron beam manufacturing (EBM)

¹Source: ASTM Standard. Standard terminology for additive manufacturing technologies, vol 10.04

Additive Manufacturing

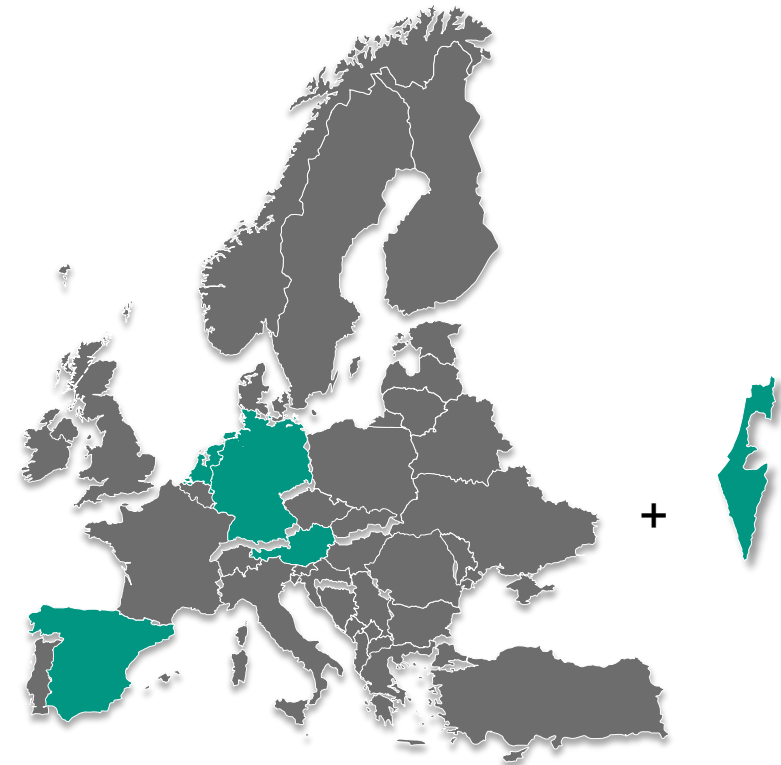
Definition & Timeline

- 2000-2010:
 - Build platforms are getting bigger, resolution is getting better, building time is reduced and prices for machines start to get lower
 - New materials are available: Nanocomposites, high-elongation materials, high temperature resistant materials, improved mechanical properties and bio-compatible materials
 - Formation of ASTM committee for producing standards on testing, processes, materials, design and terminology in AM
 - EnvisionTec introduces first stereolithography machine using direct light processing (DLP) technique

- 2010-now:
 - AM is adopted by many industries as a valid production method
 - Capabilities of machines are extended even further (materials, resolution, build sizes)
 - AM is reaching the private sector with affordable FDM, SLA and DLP printers

The project consortium

- European project und H2020 programme
- 12 partners from 5 countries
- Project duration : 2015/10-2018/09
- Budget : 5M €
- Call: H2020-NMP-PILOT-2015
- Project number : 685937



Polyjet technology

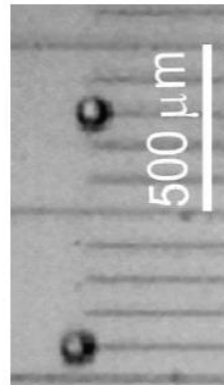
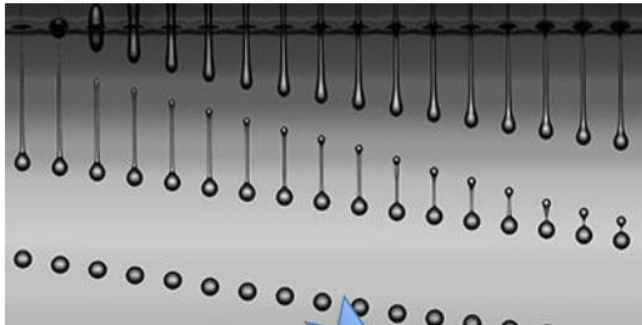
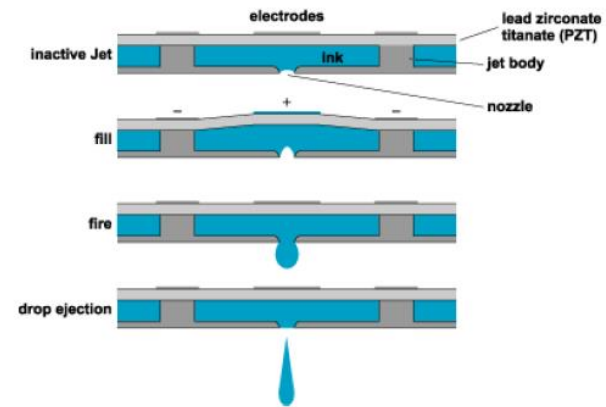


Image Courtesy of Stratasys Ltd



Few numbers....

100's of jets per head

30-80 nanograms drops

± 10 microns drop accuracy

$\pm 5\%$ drop to drop uniformity

Up to 40 KHz jetting frequency

Source: Stratasys

Polyjet technology

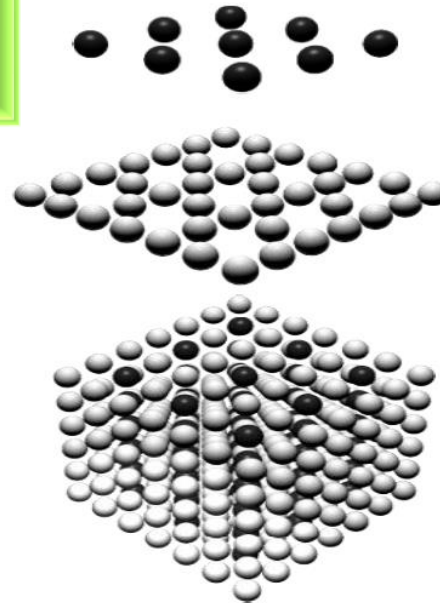
Voxel (volumetric pixel):

a volume element representing a value on a regular grid in three dimensional space.

This is analogous to a pixel, which represents 2D image data in a bitmap.



Image Courtesy of Stratasys Ltd



Black rubbery material (Tango +)

White rigid material (Vero white)

- ✓ Grey scale
- ✓ Shore hardness scale

Source: Stratasys

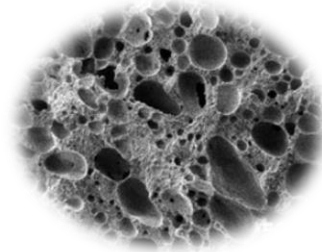
Material development

- Ceramic enhanced material



- Electrically conductive material

- Lightweight polymer material



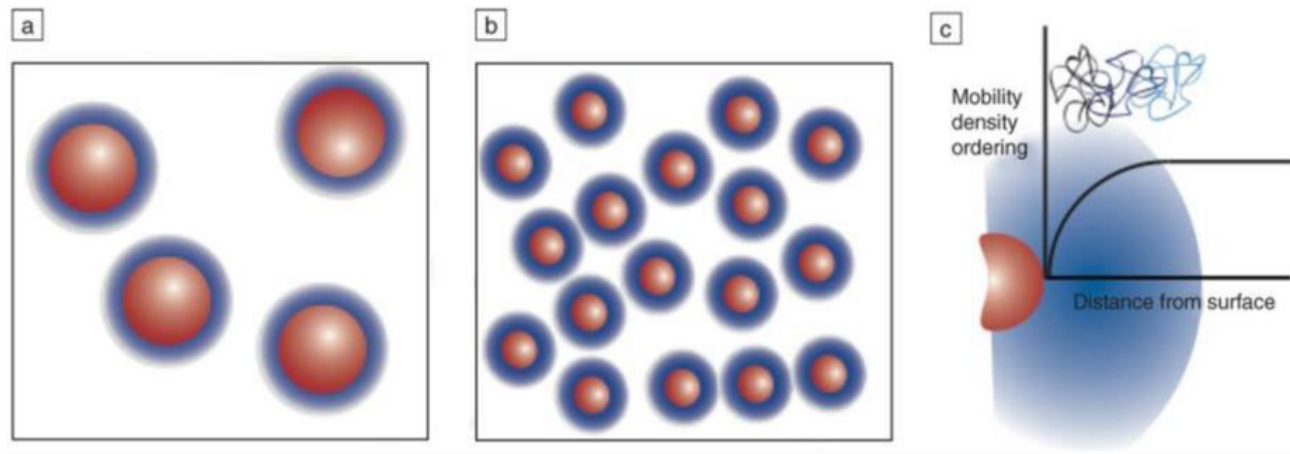
- High strength polymer material

Ceramic ink

Concept of requirements for ceramic inks

Frame conditions given by the process and the aspired applications:

- Maximum particle defined by printhead's orifice: $d_{100} < 500 \text{ nm}$
- Too much NANO is not helpful -> Increased viscosity



Compromise:
“Large”
nanoparticle size
and small specific
surface areas
needed

- a) Microsized particles, b) nanosized particles, c: Change of polymer mobility with distance from **ceramic nanoparticles**, showing a pronounced amount of immobilized polymer in the composite **causing a pronounced viscosity increase.**

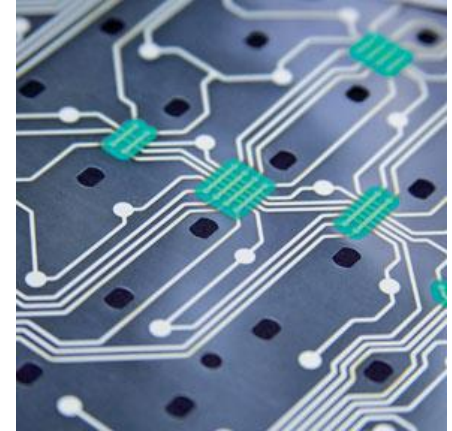
Conductive ink

Classic:

- Screen Printing and Photolithography

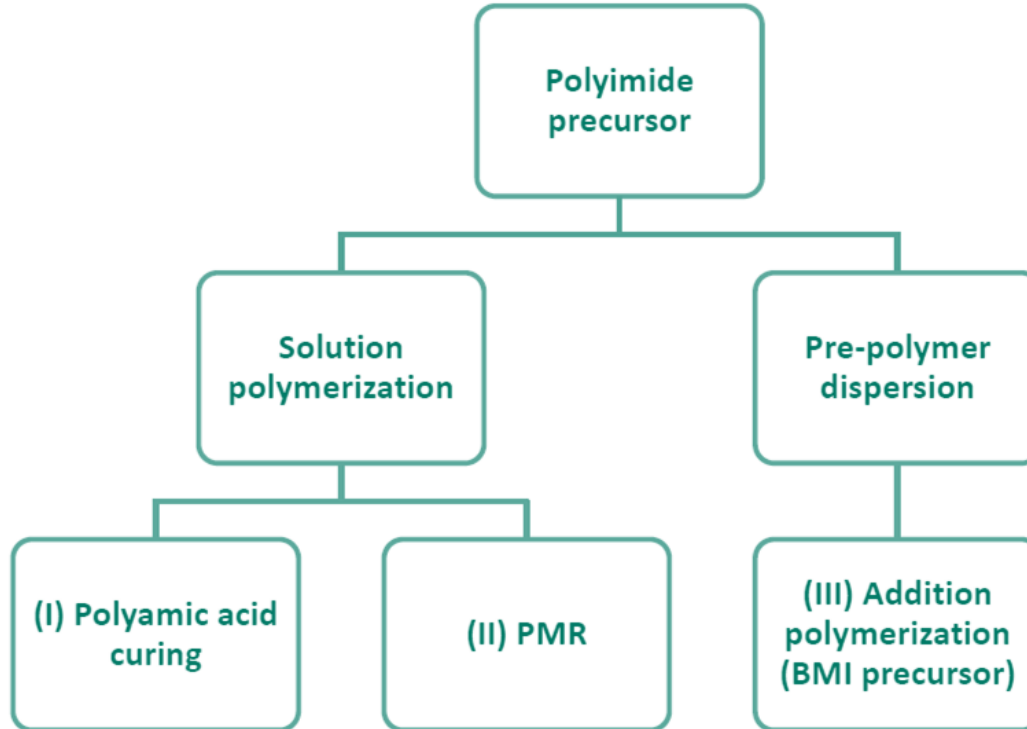
3D Printing:

- No material yet available
- > Polymer with silver nanoparticle
- > concurrent properties:
 - Low Viscosity
 - Low resistivity (High metal content)
 - Surface tension
 - Small non agglomerate particles



Parameter	Requirement	Description
Solids %	≤50% w/w (as starting points)	
Particle size	D(50) = 75-90 nm d(90) = 95-130 nm	
Viscosity	12-20cP at printing temperature (<60°C)	It is not recommended to heat PVN inks above 60°C
Surface tension	25-35 dyn/cm	
Stability test at room temperature (1 month) (Shelf life test)	Viscosity change ≤5% Particle size change ≤5%	Re-dispersible by mild shaking
Stability test at 60°C (8, 24 hours) (Stability during printing time)	Viscosity change ≤5% Particle size change ≤5%	
Accelerated sedimentation rate	<0.38 μm/sec @T=10% transmission	Tested with Lumisizer centrifuge
Jetting test	Jetting latency > 10min	

High strength ink



Initial ink requirement (STR) reveal basic limitations of solution polymerization approach

Novel approach to be studied

- High viscosity of polyimide precursors
- Slow kinetics
- High temperature tolerance needed
- Solution polymerization is a challenging process for inkjet formulation

Multi material

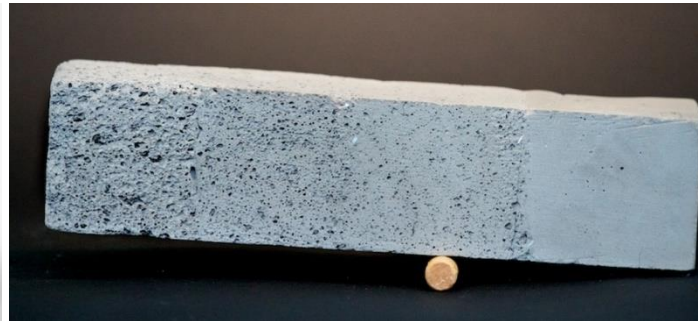
- Creation of parts with functionally graded materials:

- Hardness
- Flexibility
- Adhesive properties
- Stiffness
- Color

Image Courtesy of Kiril Vidimce



Image Courtesy of Synthesis Design + Architecture



Images Courtesy of Massachusetts Institute of Technology



- Possible Applications:

- Compliant joints
- Artistic sculptures
- Heat Dissipation



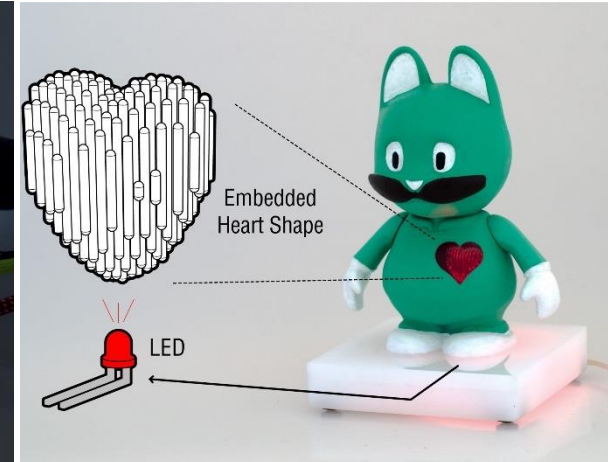
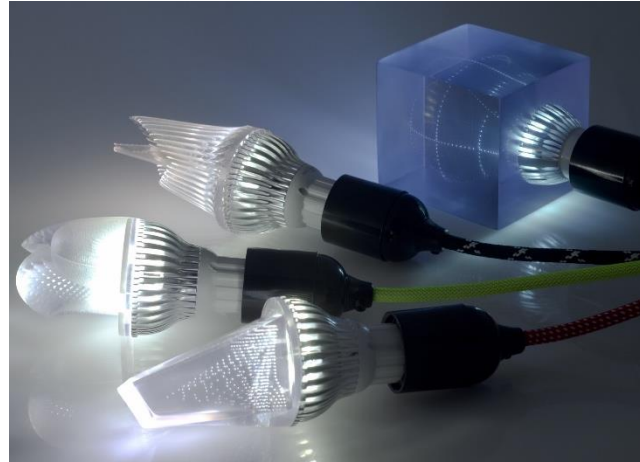
Image Courtesy of
Stratasys Inc.

Embedded components

- Objects can be embedded due to layer-by-layer build-up
 - Circuits
 - Sensors
 - Monitors
 - Threaded rods
 - Etc.



Image Courtesy of Berkeley University



Images Courtesy of Disney Research

■ Possible Applications:

- Toys
- Lighting devices
- Food monitors

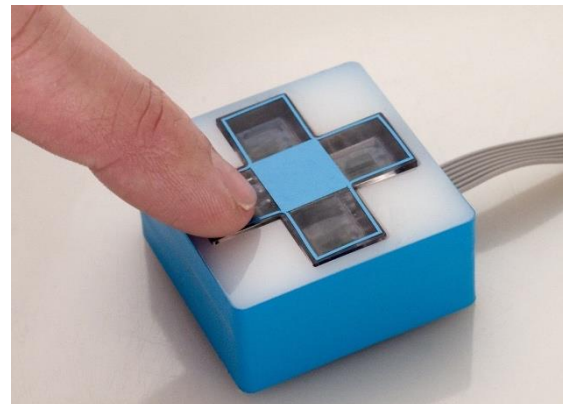


Image Courtesy of Disney Research

Printed electronics

- Pre-Assembled Parts directly printed
 - Use of sacrificial support material
 - Gaps of few hundredths μm between parts
 - Removal of support leaves captive assembled linkage
- Possible Applications:
 - Physical Working models
 - Locomotive robots
 - Articulated Models
 - Prosthetics

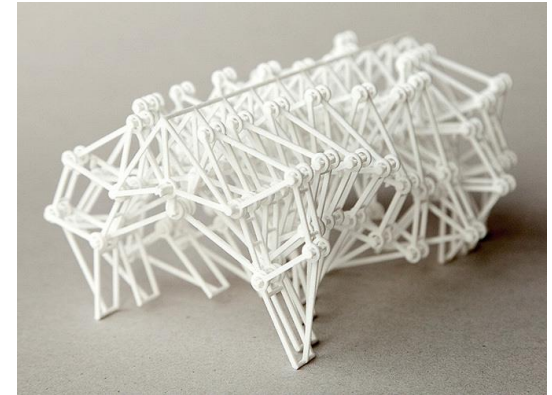
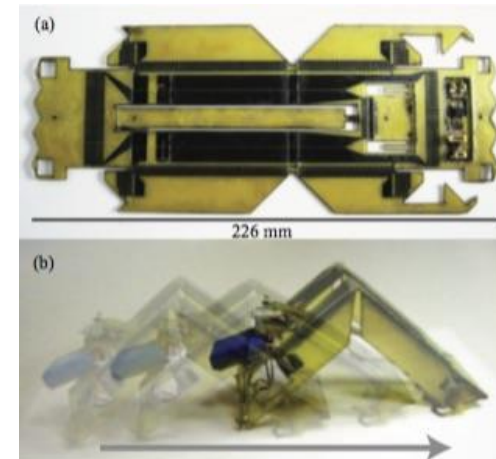


Image Courtesy of Shapeways



M. Bächer et al. „Fabricating Articulated Characters from Skinned Meshes“, ACM Trans Graph, 31 (4), 2012



S.M. Felton et al. „Robot Self-Assembly by Folding: A Printed Inchworm Robot“, ICRA Conference 2013

Additive Manufacturing – Trends & Challenges

Materials:

- Broadening of available materials; solid loaded inks & polymers
- Digital materials & integration of discrete parts
- Biomaterials (tissue scaffolds, organs)

Design:

- Specific tool representing AM functions & interactions; simplifying designing complex shapes

High throughput & build size

- Multinozzle array print head
- Integration of additional processes
- Large scale parts

Modeling, Sensing and Process Control

- Transport phenomena, temperature
- Access to build chamber for monitoring
- Integration of control algorithms

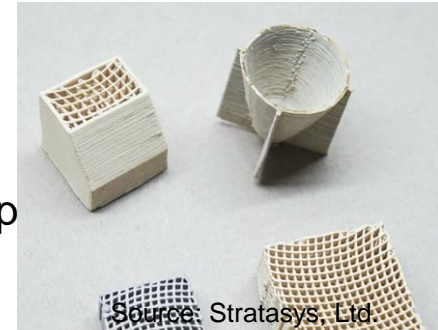


Image Courtesy of Shapeways



Steps of building process

Conclusion

- A New Industrial Revolution of connected objects is happening
 - IT Advances:
 - Cloud storage
 - Calculation capacities
 - Operation Technologies advances:
 - Digital system Integration
 - AM processes
 - Materials
- Changes to come:
 - Mass customisation
 - Higher productivity (predictive maintenance, automatization, ...)
- It is up to us to make this revolution Human-Centred
 - Improvement of Human-machine interface
 - Telepresence
 - Training

Acknowledgements

The author thanks all partners involved in the results presented and the European Committee for funding the projects shown.

